

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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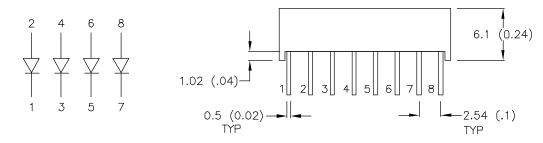






DRAWING NUMBER SSB-LXB100SRW REV

-20.04 (0*.*79)— 4 (.157)— -19.05 (0.75)-3.81 (0.15) 4.86 (0.18) L 0.25 (0.01)



UNIT: mm (INCHES) TOLERANCE: +/-0.25 (+/-0.01) UNLESS OTHERWISE SPECIFIED

ELECTRO-OPTICAL CHARACTERISTICS TA=25 °C I = 20mA

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660 (RED)		nm	
FORWARD VOLTAGE		1.7	2.2	V_{f}	
REVERSE VOLTAGE	5.0			V_r	$I_{\Gamma} = 100 u A$
AXIAL INTENSITY		80		mcd	$I_f = 20 \text{mA}$
VIEWING ANGLE		160		2x theta	·
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WHITE	DIFFUS	ED		

LIMITS OF SAFE OPERATION AT 25 DEG. C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 38 °C	-0.5	mA/ °C
OPERATING, STORAGE TEMP.	-20 TO +85	° C
LEAD SOLDERING TEMP.	+230	° C
1.6mm FROM BODY		5 SEC. MAX

^{*} t<10uS

RELIABILITY NOTE:

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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CHK'D: APPD: DWN: 4-8-93 DATE: SCALE: DO NOT SCALE DWG

19.05mm X 3.81mm LIGHT BAR, WHITE DIFFUSED

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BXB1GOAB

REV